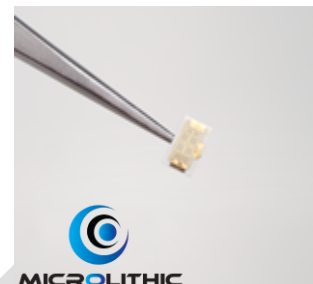


MICROLITHIC™ DOUBLER

MLD-1640

The MLD-1640 is a Microlithic™ doubler. As with all Microlithic™ devices (patent pending), it features excellent conversion loss and harmonic suppressions across a broad bandwidth and in a miniaturized form factor. Accurate, nonlinear software models are available for Microwave Office through the Marki Microwave PDK. The MLD-1640 is available as a wire bondable chip or in a connectorized package. The MLD-1640 is an excellent alternative to Marki Microwave doublers packaged in drop-in carriers such as the ES carrier.



Features

- Compact Chip Style Package (0.152" x 0.090" x 0.010")
- CAD Optimized for Superior Suppressions and Efficiency
- Excellent Unit-to-Unit Repeatability
- Fully nonlinear software models available with Marki PDK for Microwave Office
- RoHS Compliant

Note: This part is being discontinued due to material obsolescence. Please see this [EOL letter](#) for recommended replacements.

Electrical Specifications - Specifications guaranteed from -55 to +100°C, measured in a 50Ω system.

Parameter	Input (GHz)	Output (GHz)	Min	Typ	Max	Diode Option Input drive level (dBm)
2F (out) Conversion Loss (dB)	8.0-20.0	16.0-40.0		11	16	
Suppressions ¹						
1F (in) Fundamental				34		
3F (out) Third Harmonic				34		
4F (out) Fourth Harmonic				17		
Isolations ¹						
1F (in) Fundamental				46		
3F (out) Third Harmonic				45		
4F (out) Fourth Harmonic				28		
1F Input Level ²			+10		+16	L-Version

¹Suppression is relative to doubled output power. Isolation is defined as relative to the fundamental input power.

²For higher input power, alternative diode options may be available. Contact factory.

Part Number Options

Please specify diode level and package style by adding to model number.						
Package Styles		Examples				
Connectorized ¹	S	MLD-1640LCH, MLD-1640LS				
Chip ^{2,3} (RoHS)	CH	<u>MLD-1640</u> (Model)	<u>L</u> (Diode Option)	<u>CH</u> (Package)		

¹Connectorized package consists of chip package wire bonded to a substrate, equivalent to an evaluation board.

²Chip package connects to external circuit through wire bondable gold pads.

³Note: For port locations and I/O designations, refer to the drawing on page 3 of this document.

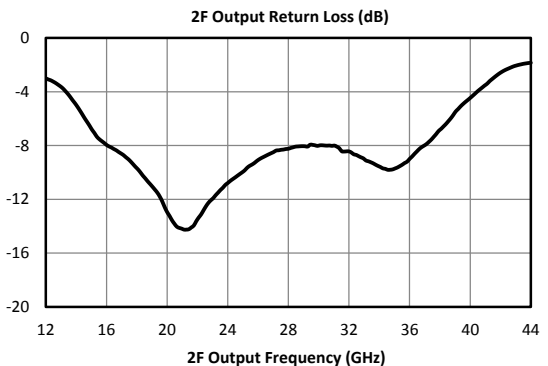
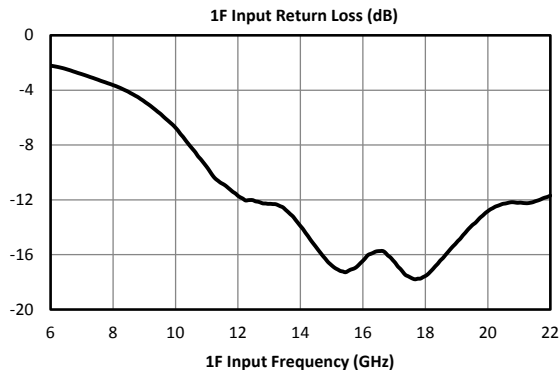
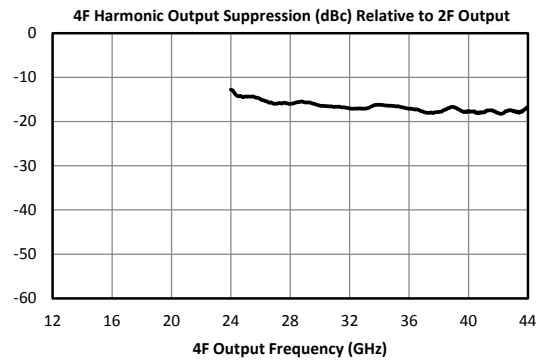
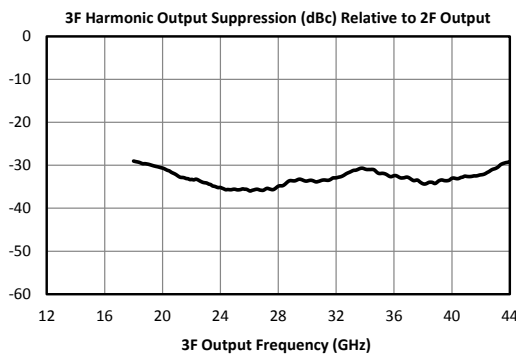
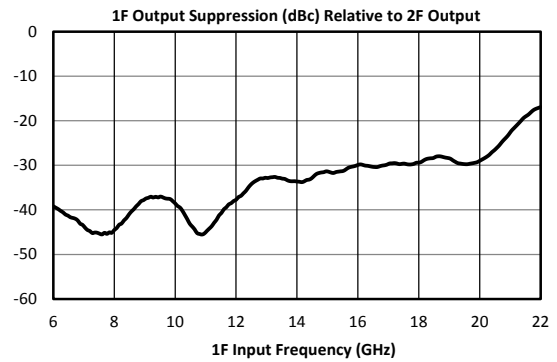
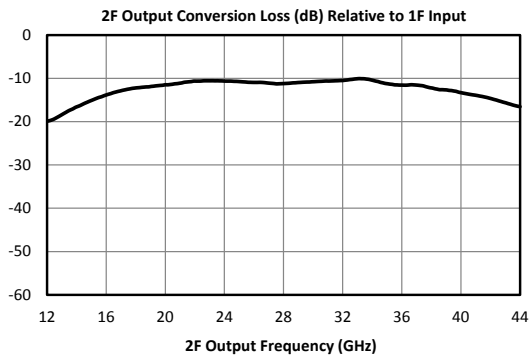
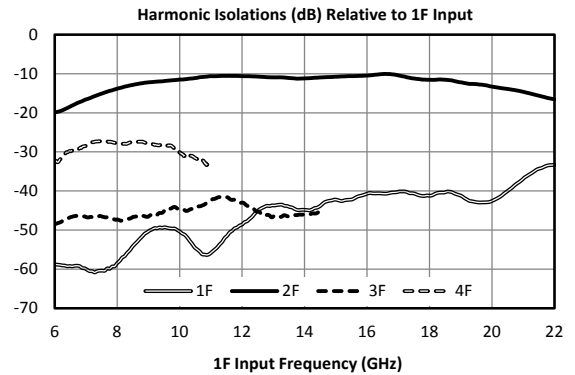
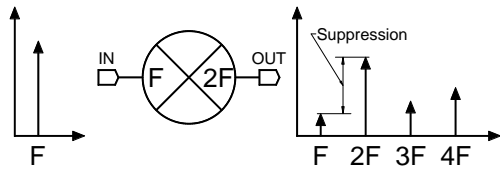
MICROLITHIC™ DOUBLER

Page 2

MLD-1640

Input 8 to 20 GHz
Output 16 to 40 GHz

Typical Performance

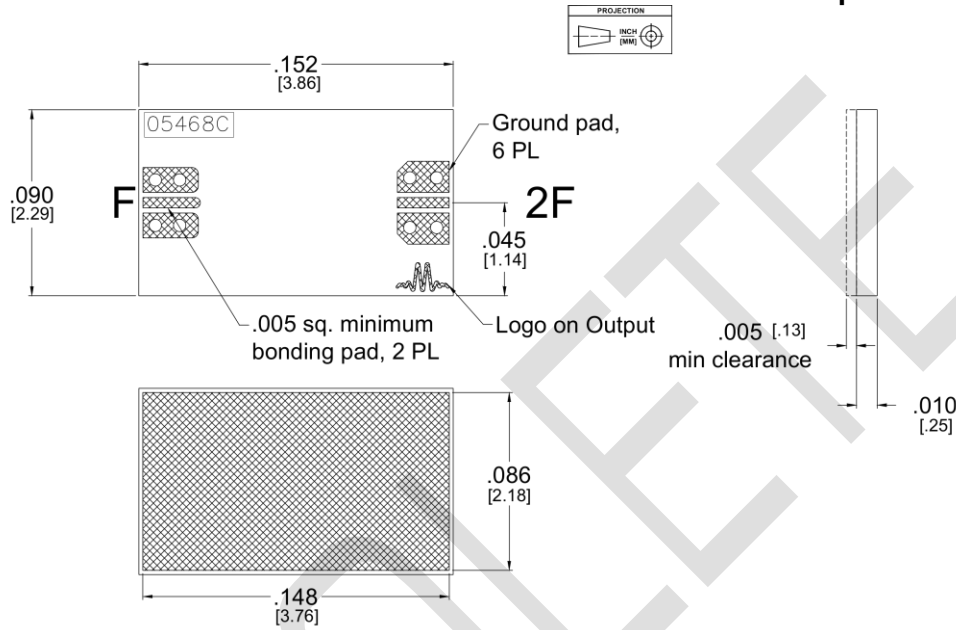


MICROLITHIC™ DOUBLER

Page 3

MLD-1640

Input 8 to 20 GHz
Output 16 to 40 GHz

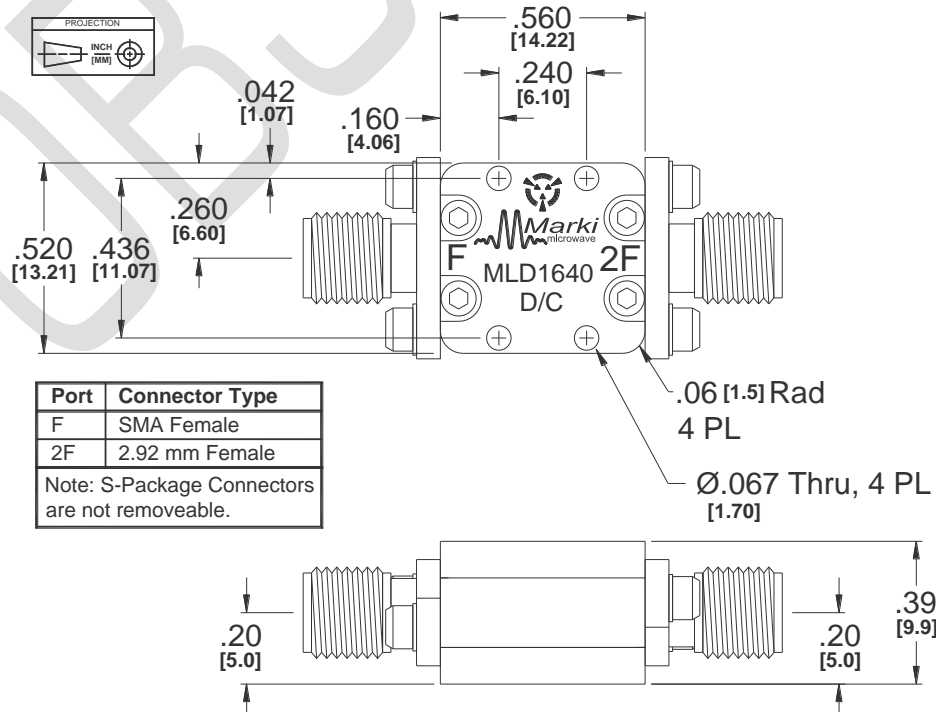


Outline Drawing – CH package

*CH Substrate material is .010 thick Ceramic.

I/O traces and ground plane finish is 2.5 microns Au over .05 microns WTI.

Wire Bonding - Ball or wedge bond with 0.025 mm (1 mil) diameter pure gold wire. Thermosonic wirebonding with a nominal stage temperature of 150 °C and a ball bonding force of 40 to 50 grams or wedge bonding force of 18 to 22 grams is recommended. Use the minimum level of ultrasonic energy to achieve reliable wirebonds. Wirebonds should be started on the chip and terminated on the package or substrate. All bonds should be as short as possible <0.31 mm (12 mils).



Outline Drawing – SD package



MICROLITHIC™ DOUBLER

Page 4

MLD-1640

Input 8 to 20 GHz
Output 16 to 40 GHz

Port	Description	DC Interface Schematic
F Input	The input port is DC short to ground and AC matched to 50 Ohms from 8 GHz to 20 GHz. Blocking capacitor is optional.	
2F Output	The output port is DC short to ground and AC matched to 50 Ohms from 16 GHz to 40 GHz. Blocking capacitor is optional.	

Absolute Maximum Ratings	
Parameter	Maximum Rating
Input DC Current	1 Amp
Output DC Current	1 Amp
RF Power Handling	+25 dBm at +25°C, derated linearly to +20 dBm at +100°C
Operating Temperature	-55°C to +100°C
Storage Temperature	-65°C to +125°C

DATA SHEET NOTES:

1. Doubled Loss typically degrades less than 0.5 dB at +100°C and improves less than 0.5 dB at -55°C.
2. Unless otherwise specified, L-Diode data is taken with a +11 dBm input.
3. Specifications are subject to change without notice. Contact Marki Microwave for the most recent specifications and data sheets.
4. Catalog doubler circuits are continually improved. Configuration control requires custom model numbers and specifications.

Marki Microwave reserves the right to make changes to the product(s) or information contained herein without notice. Marki Microwave makes no warranty, representation, or guarantee regarding the suitability of its products for any particular purpose, nor does Marki Microwave assume any liability whatsoever arising out of the use or application of any product.

© Marki Microwave, Inc.



215 Vineyard Court, Morgan Hill, CA 95037 | Ph: 408.778.4200 | Fax 408.778.4300 | info@markimicrowave.com
www.markimicrowave.com